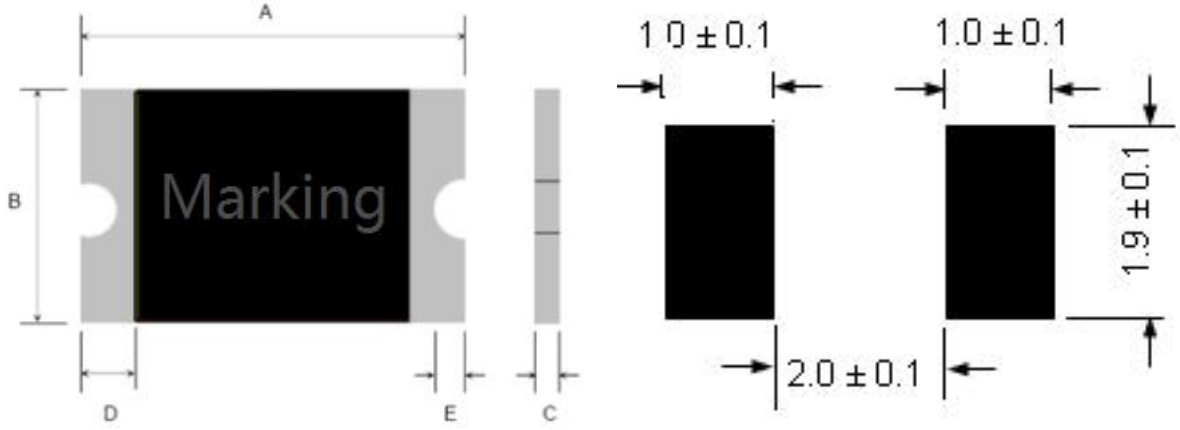
SMD1206-260-12V

Shape and Size



Terminal pad materials :Tin-Plated Nickle-copper

Terminal pad solderability : Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3

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Dimention(Unit : mm)

Model	A		B		C		D	E
	Min.	Max.	Min.	Max.	Min.	Max	Min.	Min.
SMD1206-260-12v	3.00	3.50	1.50	1.80	0.70	1.70	0.15	0.10

Electrical Characteristics:

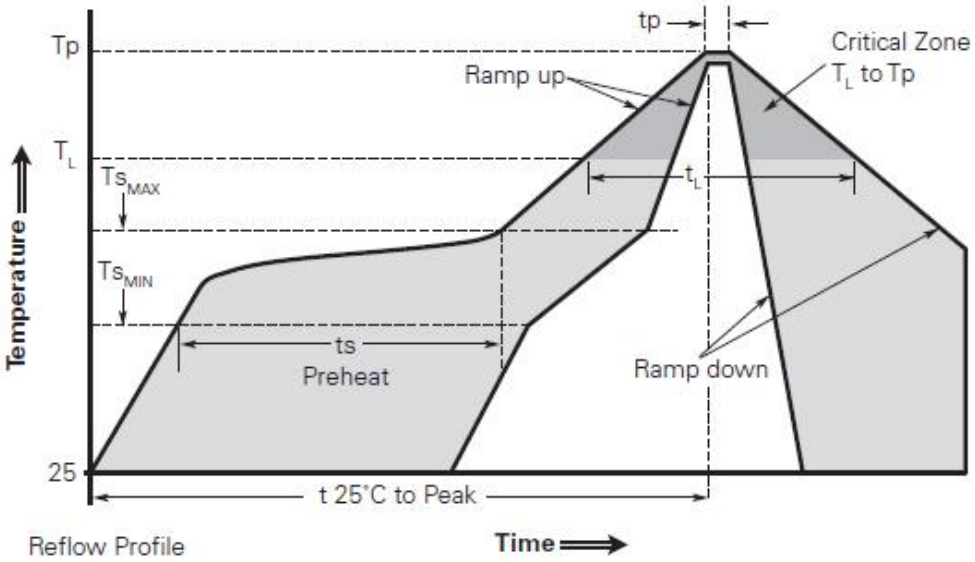
Model	V_{max} (Vdc)	I_{max} (A)	I_{hold} @25℃ (A)	I_{trip} @25℃ (A)	P_d Typ (W)	Maximum Time To Trip		Resistance		
						Current (A)	Time (Sec)	Ri_{min} (Ω)	Ri_{typ} (Ω)	$R1_{max}$ (Ω)
SMD1206-260	12.0	50.0	2.6	5.2	0.8	8.0	5.0	0.004	-	0.026

Test Conditions and Standards:

I_{tem}	Test Conditon	Standard
Initial Resistance	In still air, 25℃	0.004-0.026Ω
I_H	25℃, 2.6A, 60min	No Trip
T_{trip}	25℃, 8.0A	≤5.0 S
Trip endurance	12V, 50.0A, 60min	No arcing or burning

Operating Temperature：-40℃ TO 85℃
Packaging：Bulk 3500 pcs per bag

Solder Reflow Conditions



Profile Feature	Pb-Free Assembly
●Average ramp up rate(Ts_{MAX} to Tp)	3℃/Second max
Preheat	
●Temperature min (Ts_{MIN})	150℃
●Temperature max (Ts_{MAX})	200℃
●Time(Ts_{MIN} to Ts_{MAX})	60-120 Seconds
Time maintained above:	
●Temperature(T_L)	217℃
●Time(T_L)	60-150 Seconds
●Peak/Classification temperature(Tp)	260℃
Time within5℃ofactual peak temperature	
●Time(Tp)	30 Seconds max
●Ramp down rate	3℃Second max
●Time 25℃ to peak temperature	8 minutes max

Note：All temperatures refer topside of the package.measured on The package body surface

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temprature profile meets RoHs leadfree process.

Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

Storage

The maximum ambient temperature shall not exceed 38℃. Storage temperatures higher than 38℃ could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 60%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use. The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present

Warning

Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.

PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.

Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.

Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.PPTC SMD can be cleaned by standard methods.

· Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profilecould negatively impact solderability performance of our devices.。